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PATENT
Atty. Dkt. No: AMAT/6072/CMP/ECP/RKK

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Olgado, et al.

Serial No.: 09/981,505

Confirmation No.: 6914

Filed: October 16, 2001

For: Planarization of Metal
Layers on a
Semiconductor Wafer
Through Non-Contact De-
Plating and Control with
Endpoint Detection

Group Art Unit: 2812

Examiner: H. Jay Tsai

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SEP 10 2003
TECHNOLOGY CENTER 2800Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

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37 CFR 1.8	
I hereby certify that this correspondence is being deposited on	
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8/29/03	<i>[Signature]</i>
Date	Signature

RESPONSE TO OFFICE ACTION DATED JUNE 4, 2003

In response to the Office Action dated June 4, 2003, having a shortened statutory period for response set to expire on September 4, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/6072/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper. **Remarks/Arguments** begin on page 6 of this paper.